



FDMS8820

N-Channel PowerTrench® MOSFET 30 V, 116 A, 2.0 mΩ

Features

- Max $r_{DS(on)}$ = 2.0 mΩ at $V_{GS} = 10$ V, $I_D = 28$ A
- Max $r_{DS(on)}$ = 2.4 mΩ at $V_{GS} = 4.5$ V, $I_D = 25$ A
- Advanced Package and Silicon combination for low $r_{DS(on)}$ and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

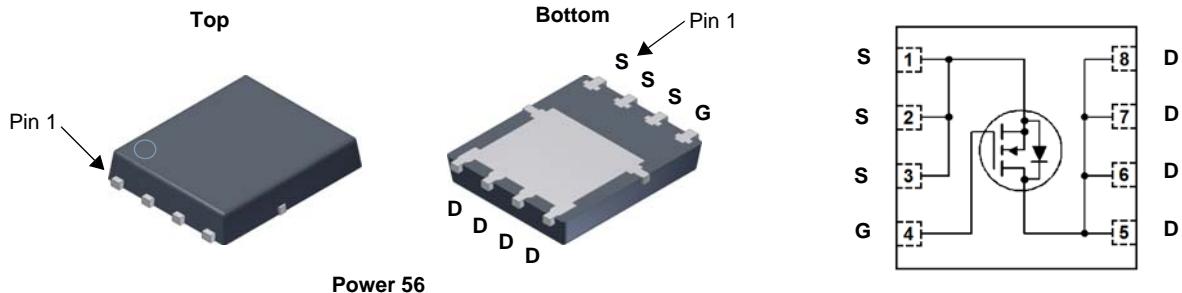


General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(on)}$, fast switching speed and body diode reverse recovery performance.

Applications

- VRM Vcore Switching for Desktop and Server
- O-ringFET / Load Switching
- DC-DC Conversion



MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current -Continuous $T_C = 25$ °C	116	A
	-Continuous $T_A = 25$ °C (Note 1a)	28	
	-Pulsed (Note 5)	180	
E_{AS}	Single Pulse Avalanche Energy (Note 3)	294	mJ
P_D	Power Dissipation $T_C = 25$ °C	78	W
	Power Dissipation $T_A = 25$ °C (Note 1a)	2.5	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.6	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS8820	FDMS8820	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
$BVDSS$	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	30			V
$\Delta BVDSS$ ΔT_J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, referenced to 25°C		19		$\text{mV}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
I_{GSS}	Gate to Source Leakage Current, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

On Characteristics

$V_{GS(\text{th})}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	1.2	1.5	2.5	V
$\Delta V_{GS(\text{th})}$ ΔT_J	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, referenced to 25°C		-6		$\text{mV}/^\circ\text{C}$
$r_{DS(\text{on})}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 28 \text{ A}$		1.4	2.0	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 25 \text{ A}$		1.8	2.4	
		$V_{GS} = 10 \text{ V}, I_D = 28 \text{ A}, T_J = 125^\circ\text{C}$		2.0	2.8	
g_{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_D = 28 \text{ A}$		76		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		3995	5315	pF
C_{oss}	Output Capacitance			1295	1725	pF
C_{rss}	Reverse Transfer Capacitance			177	270	pF
R_g	Gate Resistance		0.1	1.1	2.5	Ω

Switching Characteristics

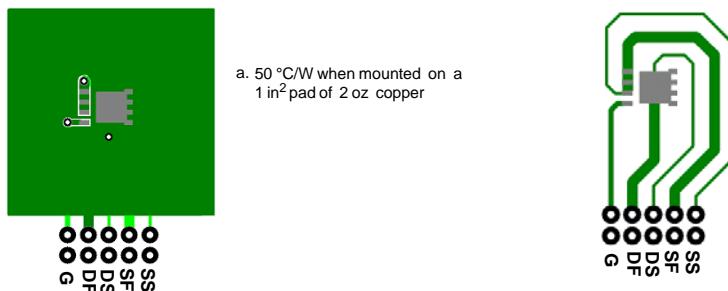
$t_{d(\text{on})}$	Turn-On Delay Time	$V_{DD} = 15 \text{ V}, I_D = 28 \text{ A}, V_{GS} = 10 \text{ V}, R_{\text{GEN}} = 6 \Omega$		14	25	ns
t_r	Rise Time			7.7	16	ns
$t_{d(\text{off})}$	Turn-Off Delay Time			41	66	ns
t_f	Fall Time			6.4	13	ns
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ V} \text{ to } 10 \text{ V}$		63	88	nC
	Total Gate Charge		$V_{DD} = 15 \text{ V}, I_D = 28 \text{ A}$	30	42	nC
Q_{gs}	Gate to Source Charge	$V_{GS} = 0 \text{ V} \text{ to } 4.5 \text{ V}$		9.8		nC
Q_{gd}	Gate to Drain "Miller" Charge			8.2		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.0 \text{ A}$ (Note 2)		0.7	1.1	V
		$V_{GS} = 0 \text{ V}, I_S = 28 \text{ A}$ (Note 2)		0.8	1.2	
t_{rr}	Reverse Recovery Time	$I_F = 28 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		43	69	ns
Q_{rr}	Reverse Recovery Charge			27	43	

Notes:

1. R_{QJA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{QJC} is guaranteed by design while R_{QCA} is determined by the user's board design.



a. $50^\circ\text{C}/\text{W}$ when mounted on a 1 in² pad of 2 oz copper

b. $125^\circ\text{C}/\text{W}$ when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0%.

3. E_{AS} of 294 mJ is based on starting $T_J = 25^\circ\text{C}$; N-ch: $L = 3 \text{ mH}, I_{AS} = 14 \text{ A}, V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}$. 100% test at $L = 0.1 \text{ mH}, I_{AS} = 45 \text{ A}$.

4. As an N-ch device, the negative V_{GS} rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

5. Pulsed I_D limited by junction temperature, $td = 100\mu\text{s}$, please refer to SOA curve for more details.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

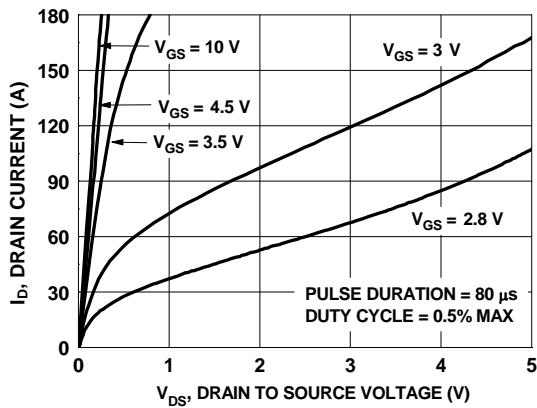


Figure 1. On Region Characteristics

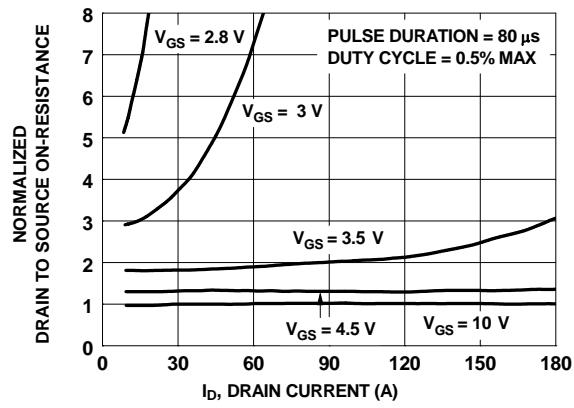


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

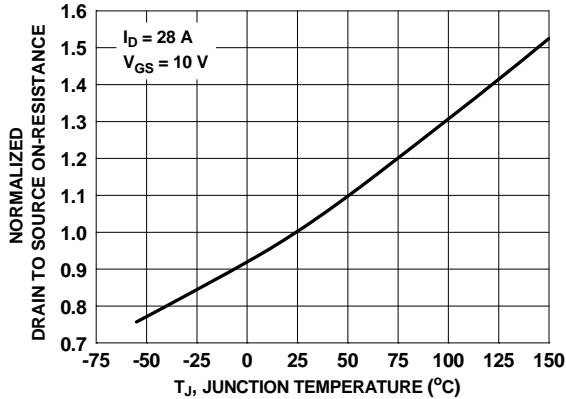


Figure 3. Normalized On Resistance vs Junction Temperature

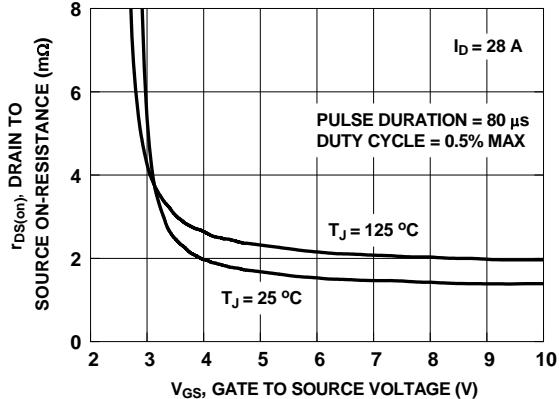


Figure 4. On-Resistance vs Gate to Source Voltage

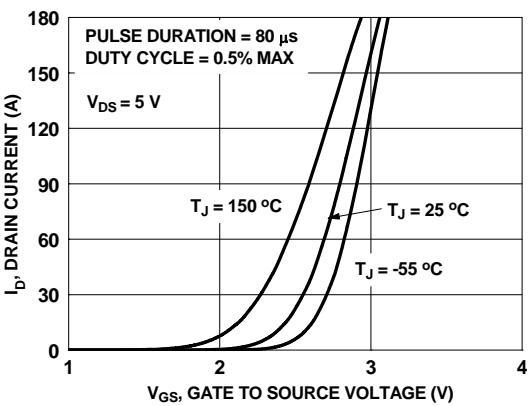


Figure 5. Transfer Characteristics

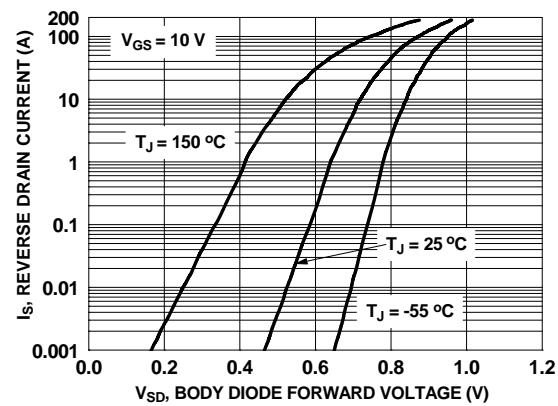


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

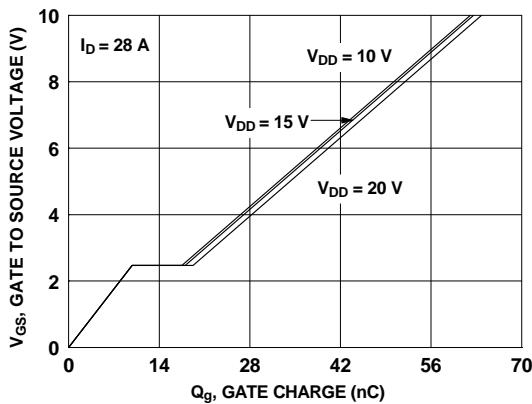


Figure 7. Gate Charge Characteristics

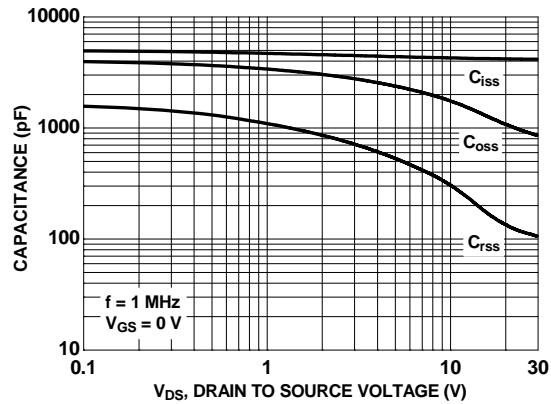


Figure 8. Capacitance vs Drain to Source Voltage

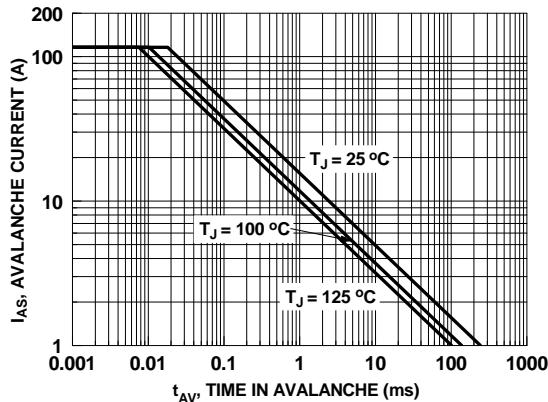


Figure 9. Unclamped Inductive Switching Capability

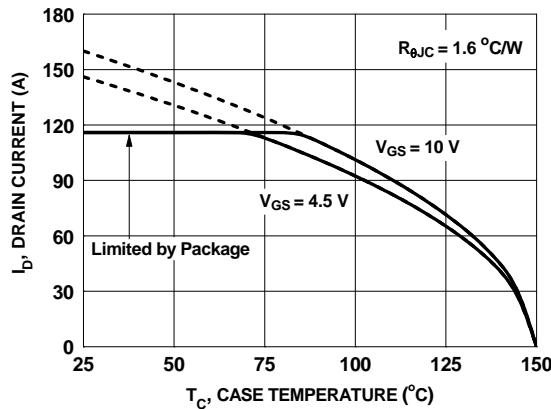


Figure 10. Maximum Continuous Drain Current vs Case Temperature

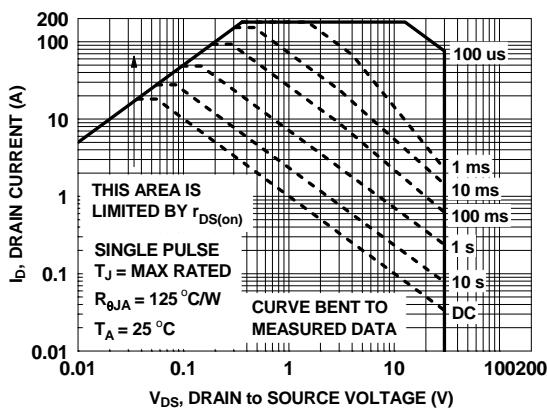


Figure 11. Forward Bias Safe Operating Area

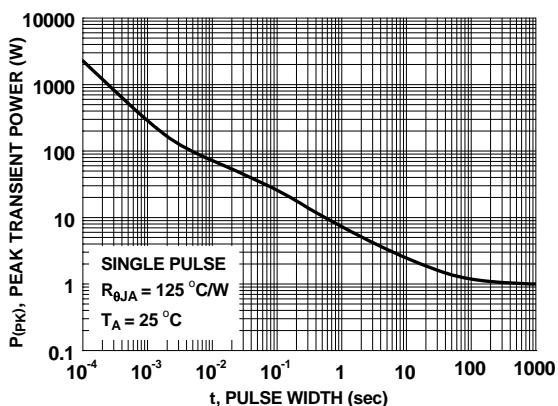


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

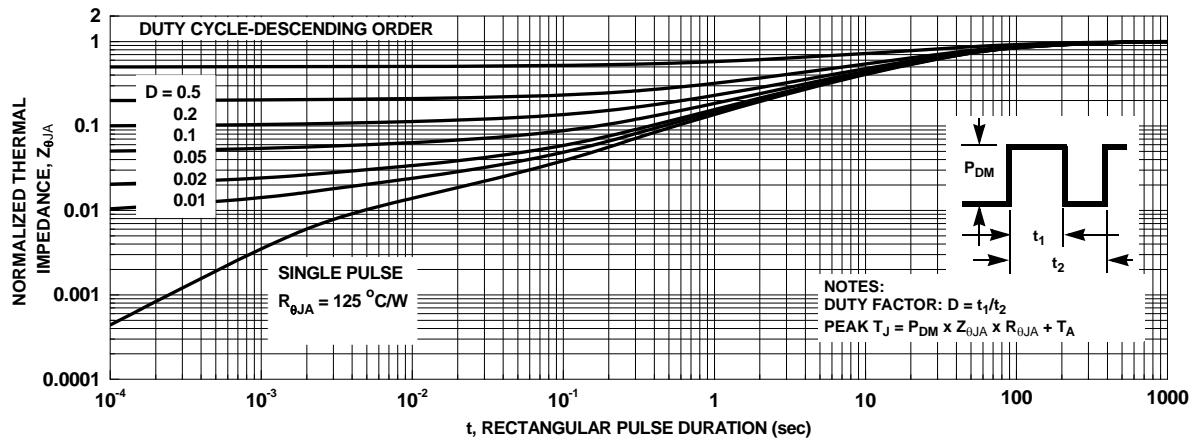
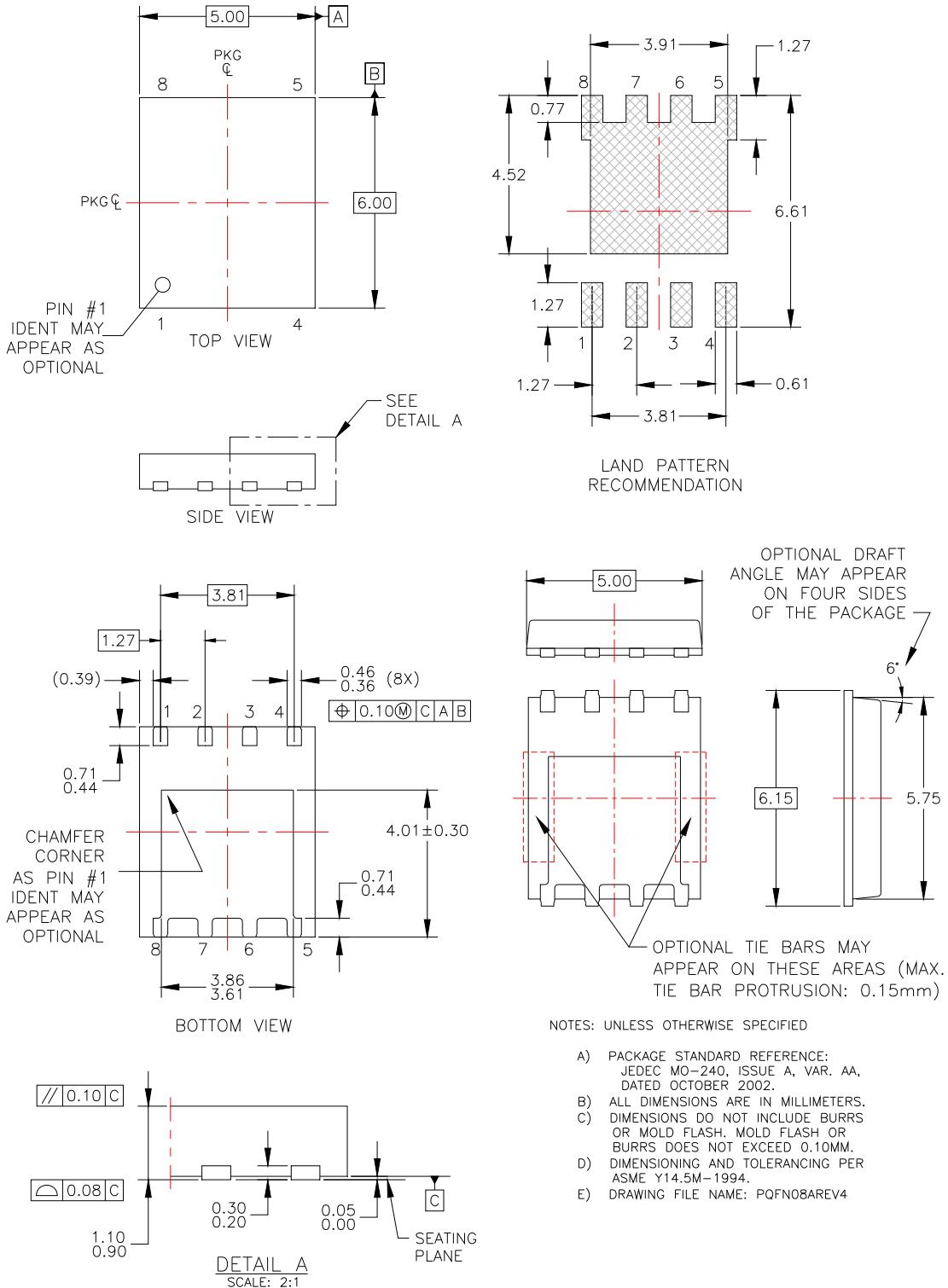


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Dimensional Outline and Pad Layout





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